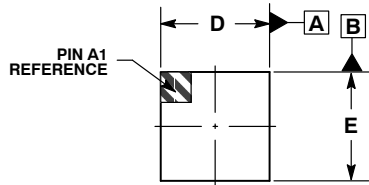




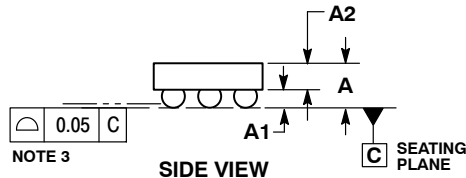
SCALE 4:1

WLCSP9, 1.2x1.2x0.48
CASE 567UL
ISSUE A

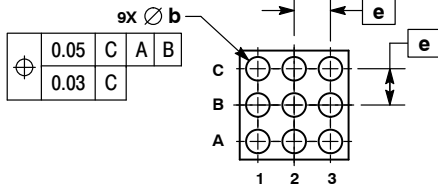
DATE 07 JUL 2017



TOP VIEW



SIDE VIEW



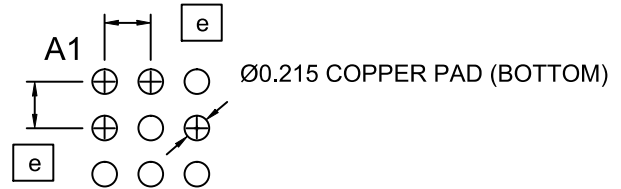
BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.450	0.488	0.526
A1	0.176	0.196	0.216
A2	0.274	0.292	0.310
b	0.24	0.26	0.28
D	1.14	1.20	1.26
E	1.14	1.20	1.26
e	0.40 BSC		

RECOMMENDED
SOLDERING FOOTPRINT*
(NSMD PAD TYPE)



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP9, 1.2x1.2x0.48	PAGE 1 OF 1

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